



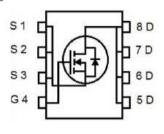
# MJ N-Channel Super Trench II Power MOSFET

### Description

The series of devices uses Super Trench II technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of R<sub>DS(ON)</sub> and Qg. This device is ideal for high-frequency switching and synchronous rectification.

#### General Features

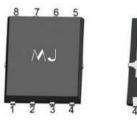
- ◆ Vps=85V lp=75A  $R_{\text{DS(ON)}}\text{=}5.6m\Omega$  , typical @ V\_Gs=10V  $R_{DS(ON)}=7.6m\Omega$ , typical @ V<sub>GS</sub>=4.5V
- ◆ Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance RDS(on)
- 150°C operating temperature
- ◆ Pb-free lead plating



Schematic Diagram

#### Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification



DFN 5X6





**Bottom View** 

100% UIS TESTED! 100% ΔVds TESTED!

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJXP075N85AGU	MJXP075N85AGU	DFN5X6-8L	-	-	8

#### Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	85	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	75	А
Drain Current-Continuous(Tc =100°C)	<b>I</b> D(100℃)	55	А
Pulsed Drain Current	Ірм	300	А
Maximum Power Dissipation	Po	95	W
Derating factor		0.76	W/°C
Single pulse avalanche energy (Note 4)	Eas	352	mJ
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 150	°C

#### Thermal Characteristic

Thermal Resistance, Junction-to-Case ReJC 1.32 °C/W	Thermal Resistance,Junction-to-Case	Rejc	1.32	°C/W
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## Electrical Characteristics (Tc=25℃ unless otherwise noted)

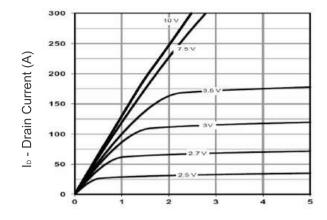
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	85	_	-	V
Zero Gate Voltage Drain Current	loss	Vps=85V,Vgs=0V	-	-	1	μA
Gate-Body Leakage Current	lgss	V <sub>DS</sub> =±20V,V <sub>DS</sub> =0V	_	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	1.2	1.7	2.2	V
Davie Course On Otata Pariatana	D	Vgs=10V,Ip=37.5A	-	5.6	- 1 - ±100  .7	mΩ
Drain-Source On-State Resistance	RDS(ON)	V <sub>GS</sub> =4.5V,I <sub>D</sub> =37.5A	_	7.6	9.0	mΩ
Forward Transconductance	grs	V <sub>DS</sub> =5V,I <sub>D</sub> =37.5A	-	50	-	S
Dynamic Characteristics (Note 3)	1		1			
Input Capacitance	Clss	V <sub>DS</sub> =40V,V <sub>GS</sub> =0V F=1.0MHz	_	2650	-	PF
Output Capacitance	Coss		-	410	-	PF
Reverse Transfer Capacitance	Crss	•	-	25	-	PF
Switching Characteristics (Note 3)	-		1			
Turn-on Delay Time	t <sub>d(on)</sub>		-	14	-	nS
Turn-on Rise Time	tr	- Vdd=40V,ld=37.5A	_	31	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =10V,R <sub>G</sub> =1.6Ω	_	29	_	nS
Turn-Off Fall Time	tr		-	7	-	nS
Total Gate Charge	Qg		-	52	-	nC
Gate-Source Charge	Qgs	V <sub>DS</sub> =40V,I <sub>D</sub> =37.5A V <sub>GS</sub> =10V	_	10	_	nC
Gate-Drain Charge	Qgd	VGS-10V	-	14	_	nC
Drain-Source Diode Characteristics				<u> </u>		
Diode Forward Voltage (Note 2)	Vsp	V <sub>GS</sub> =0V,I <sub>S</sub> =37.5A	_	_	1.2	V
Diode Forward Current	Is		_	_	75	A
Reverse Recovery Time	trr		_	55	_	nS
Reverse Recovery Charge	Qrr	TJ=25°C,IF=37.5A di/dt= 100A/µs (Note 3)	_	98	_	nC
Travelse recovery onlinge	Qrr			30		110

#### Notes:

- 1) Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3 Guaranteed by design, not subject to production
- 4 EAS condition : Tj=25°C,Voo=50V,Vo=10V,L=0.25mH,Rg=25 $\Omega$

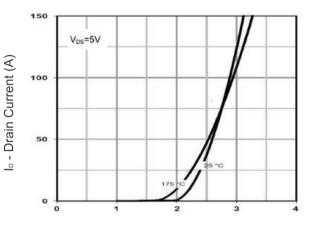


### Typical Electrical and Thermal Characteristics



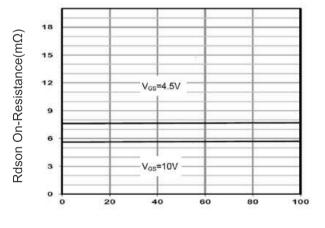
Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



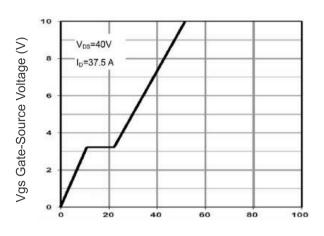
Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



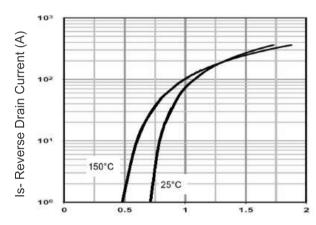
l⊳ - Drain Current (A)

Figure 3 Rdson- Drain Current



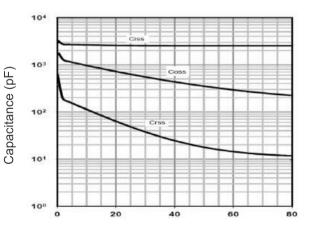
Qg Gate Charge (nC)

Figure 4 Gate Charge



Vsd Source-Drain Voltage (V)

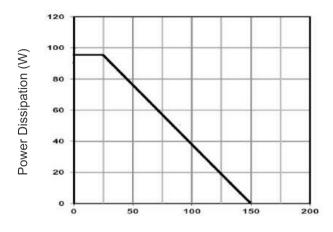
Figure 5 Source- Drain Diode Forward

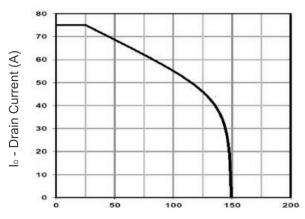


Vds Drain-Source Voltage (V)

Figure 6 Capacitance vs Vds



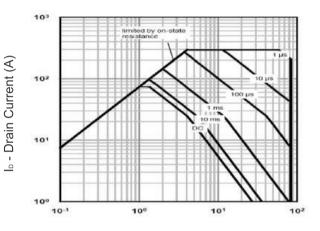


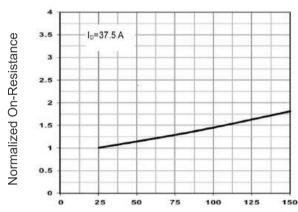


T<sub>J</sub>-Junction Temperature(°C)

Figure 7 Power De-rating

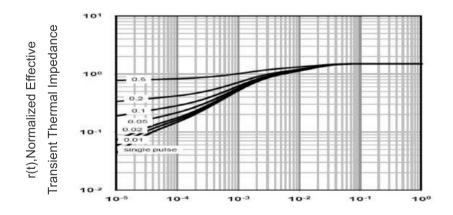
T<sub>J</sub>-Junction Temperature(°C)
Figure 9 Current De-rating





Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area

T<sub>J</sub>-Junction Temperature(°C)
Figure 10 Rdson-Junction Temperature



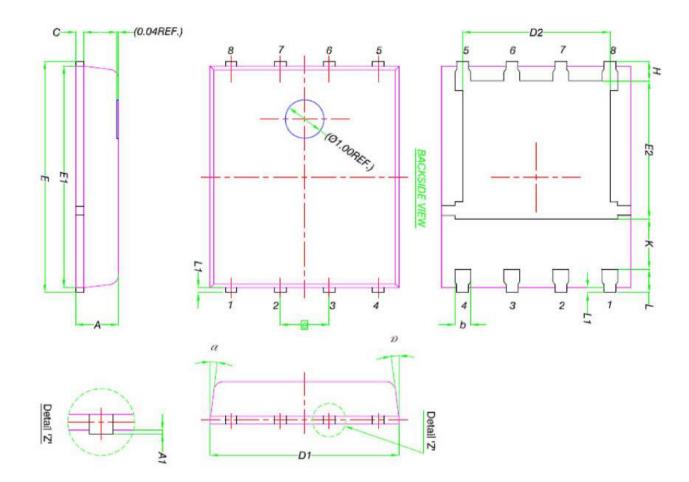
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

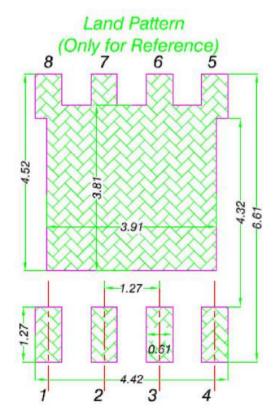




## DFN5X6-8L Package Information



044	MILLIMETERS			
DIM.	MIN.	NOM. 1.00 - 0.41 0.25 4.90 3.81 6.00 5.75 3.58	MAX.	
Α	0.90	1.00	1.10	
A1	0		0.05	
b	0.33	0.41	0.51	
С	0.20	0.25	0.30	
D1	4.80	4.90	5.00	
D2	3.61	3.81	3.96	
Ε	5.90	6.00	6.10	
E1	5.70	5.75	5.80	
E2	3.38	3.58	3.78	
е	1.27 BSC			
Н	0.41	0.51	0.61	
K	1.10		*	
L	0.51	0.61	0.71	
L1	0.06	0.13	0.20	
α	O°	-	12°	





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